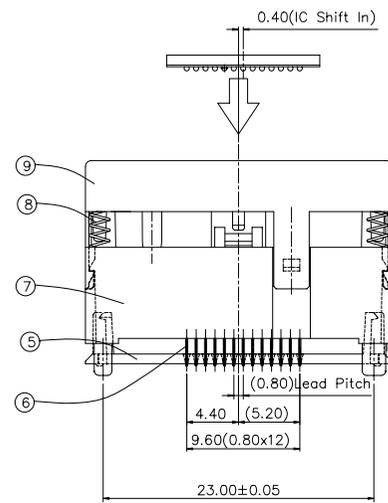
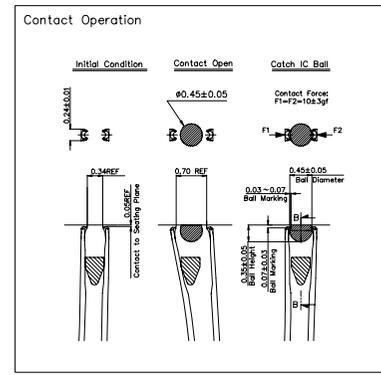
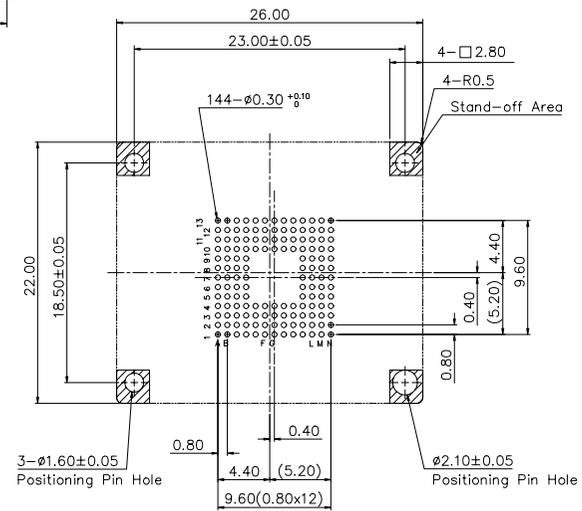


When mounting the socket onto burn-in board, pull down the lead-guide as shown on the side view below. And align the positioning pins with the through holes of the burn-in boards properly. Press the socket down from the top evenly and gradually until the socket base stand-off lie on the burn-in board.

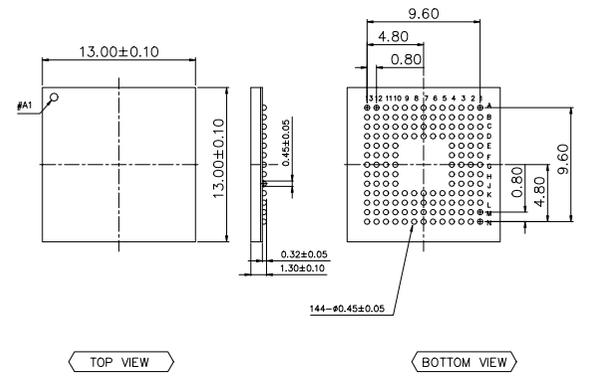
PCB Layout(TOP VIEW)



SPECIFICATION	
CONTACT RESISTANCE	50mΩ or less at 10mA , 20mV.(initial)
DIELECTRIC WITHSTANDING VOLTAGE	100VAC for 1 Minute
INSULATION RESISTANCE	1000MΩ or more at 100VDC
OPERATING TEMPERATURE	-40°C to +150°C
ACTUATION FORCE	Max 2.5Kg(1.8kg)

PARTS LIST				
NO	NAME	MATERIAL	Q'TY	FINISH
1	ADAPTER	PEI(GF)	1	(Black)
2	SLIDER	PEI(GF)	1	(Black)
3	STOPPER	PEI(GF)	1	(Black)
4	LATCH SPRING	SUS	2	
5	LEAD GUIDE	PEI(GF)	1	
6	CONTACT	BeCu	144	Ni+Au
7	BASE	PEI(GF)	1	(Black)
8	COVER SPRING	SUS	4	
9	COVER	PEI(GF)	1	(Black)
10	LATCH	PEI(GF)	2	(Black)
11	SLIDER SPRING	SUS	1	

IC Dimension



144-BGA-13.0x13.0

DRAWN	DATE	DWG NO
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Operating Method

- IC Inserting Operation
 - Push the cover all the way down(3mm) until it stops then insert the IC on top of Adapter Part NO 1. When inserting the IC PKG it's center should not be the same as that of the socket.
 - To lock the IC in place, release the cover.

- IC Removing Operation

Push the cover all the way down(3mm) until it stops then take the IC out.

(When the cover is pushed down, a vacuum method can be used to pull out the IC.)

			DRAWN	DATE	
			03/02/10		
			DESIGNED	D.W.Hwang	
			CHECKED		TITLE
REF.	NEXT ASS'Y	USED ON	VERIFIED		BGA Socket-22x26
COMMON TOLERANCES			APPROVED		144-BGA-13.0X13.0
NUMERIC	ANGLE		D.W.Hwang		SIZE
± 0.10	±				A3
					DWG NO
					SB2144E-KA
					SCALE 1/1
					UNIT mm
					SHEET 1 OF 1